

Hot Bar Reflow Soldering & Bonding

Hot an technology is well to react an electromechanical interconnection between one or more materials.

Depending on the material specifications, part design and required functionality of the end product, a specific Hot Bar process can be used.



SOLDERING & BONDING

Methods

- Hot Bar Reflow Soldering [1]
- Heat-Seal Bonding [2]
- ACF Laminating [3]
- ACF Final Bonding [2]
- Heat-Staking [4]

Products



Hot Bar Desktop Series

- NH-3000A Series Heat Seal Bonding System CH (formerly known as MHSB)
- NH-3000A Series ACF Final Bonding system PH (formerly known as MHSB)
- NH-2000A Series Pulsed Heat Reflow Soldering System (formerly known as MHBR)
- <u>NH-4000A Series ACF Laminating System (formerly known as MACFL)</u>

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Hot Bar Desktop Series

- <u>ACF Laminating/Pre-Bonding desktop systems</u>
- Heat Staking desktop systems
- Reflow Soldering Desktop Systems

Heat-Seal/ACF Final Bonding Desktop Systems



Hot Bar Modules

- Bonding Heads
- Thermo-plane Thermodes
- Interposer Module
- UF-2000A / UF-4000A / UF-R4000A Power Supply (formerly known as UNIFLOW4, UNIFLOW 4R)

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Hot Bar Systems

- Jupiter Hot Bar Bonding systems
- Jupiter Heat Staking systems
- Jupiter ACF Bonding systems

[8]



LCD/TFT & PDP Production & Repair Systems

- EM Series LCD/TFT & PDP Production & Repair Constant Heat Systems (formerly known as Emerald)
- EM Series LCD/TFT & PDP Production & Repair Pulsed Heat Systems (formerly known as Emerald)

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- MG-300A Premium Hot Bar Monitoring System (formerly known as MG)
- Process Calibration Tools

[10]

Customized Solutions

Send your sample to one of our technology centers in Europe for an evaluation. We will then determine which solution meets your needs best. AMADA WELD TECH offers feasibility testing and application consulting.

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